



Client is in the semiconductor industry by developing strategic competencies, innovative technologies and intellectual property; enabling enterprises to be technologically competitive; and cultivating a technology talent pool to inject new knowledge to the industry.

## **MICROSYSTEMS, MODULES & COMPONENTS LABORATORY**

### **Senior Research Engineer - Advanced Packaging**

This position deals with the design and development of advanced interconnection methods and packaging scheme for electronic devices, with emphasis on Micro-bump, Through Silicon Via and Cu-Cu bonding.

#### **Responsibilities:**

The key responsibility will include micro-joint design using solder, direct Cu-Cu bonding etc. Process integration for advanced packaging using Through Silicon Via, Multiple die stacking

#### **Requirements:**

- PhD degree in Mechanical engineering or Material science
- Experience in Flip-chip assembly, solder joint, underfilling
- Knowledge in Cu-Cu bonding, hybrid bonding
- Hands-on experience on micro-interconnection and reliability analysis
- Knowledge of Through Silicon Via process
- Excellent communication skills and teamwork with strong self-motivation
- Experience in project scoping and execution

**Interested candidates are invited to submit your latest updated resume stating your availability of employment, current, achievements and expected salary to Adrian Collin Png at: [adrian@collincrawford.com](mailto:adrian@collincrawford.com)**